Amendments To The Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1-35. (Cancelled).

36. (New) A method comprising:

providing a first substrate, the first substrate having a first conductor formed thereon;

disposing at least one micro-component adapted to emit radiation at a first location on the first substrate corresponding to the first conductor;

forming a dielectric layer on the first substrate;

forming a second conductor on the dielectric layer to interact with the first conductor to excite the micro-component; and

applying a top layer over the dielectric layer and the second conductor.

37. (New) The method of claim 36, wherein the step of forming a dielectric layer on the first substrate comprises:

depositing a liquid dielectric material onto the first substrate to electrically isolate the micro-component from any other micro-component on the first substrate; and

curing the liquid dielectric material to form a dielectric layer.

38. (New) The method of claim 36, wherein the step of forming the second conductor comprises:

depositing a conductive liquid on top of the dielectric layer at a second location adapted to interact with the first conductor to excite the micro-component; and

curing the conductive liquid to create a conductive layer for providing the second conductor.

39. (New) The method of claim 36, further comprising:

coating the micro-component with a phosphor material.

40. (New) The method of claim 36, further comprising:

immersing the micro-component in a slurry of phosphor particles to form a phosphor coating; and

curing the phosphor coating formed on the micro-component.

41. (New) The method of claim 38, further comprising:

depositing a liquid black mask layer onto the first substrate and the conductive layer; and

curing the liquid mask material to form a black mask layer.

42. (New) The method of claim 38, further comprising:

photolithographically patterning the conductive layer to form the second conductor.

43. (New) The method of claim 42, wherein the step of photolithographically patterning comprises:

selectively exposing a photosensitive material by contacting the photosensitive material with a leaky optical waveguide.

44. (New) The method of claim 36, wherein the first substrate has a dimple formed therein at the first location.

45. (New) The method of claim 44, wherein an adhesive material is applied within the dimple for securing the micro-component in the dimple.

46. (New) The method of claim 38, wherein the step of depositing a conductive liquid comprises printing an electrode pattern with a conductive ink.

47. (New) The method of claim 46, wherein the printing comprises inkjet printing.

48. (New) The method of claim 37, wherein the liquid dielectric material has a surface tension adapted to provide a uniform thickness across the first substrate.

49. (New) The method of claim 37, wherein the liquid dielectric material includes a surfactant.

50. (New) The method of claim 36, further comprising disposing an RF screen over the top layer.

51. (New) A method comprising:

providing a first dielectric substrate material;

printing an electrode on the first dielectric material;

forming a socket at a location in the first dielectric material;

disposing a micro-component adapted to emit light in the socket;

forming a dielectric layer on the first dielectric material;

printing a second electrode over the dielectric layer; and

applying a top layer over the dielectric layer, the second electrode, and the micro-component.

52. (New) The method of claim 51, wherein the step of providing the first dielectric substrate material comprises:

feeding the first dielectric substrate material from a payout reel in a web coating machine.

53. (New) The method of claim 51, wherein the step of forming a dielectric layer on the first dielectric material comprises:

applying a liquid dielectric material over the first dielectric material, the first plurality of electrodes, and at least a portion of the micro-component; and

curing the liquid dielectric material to form the dielectric layer.

54. (New) The method of claim 51, wherein the step of printing the second electrode over the dielectric layer comprises:

printing the second electrode over the dielectric layer using a conductive ink; and

curing the conductive ink.

55. (New) The method of claim 51, further comprising:

applying an adhesive material within the socket for securing the micro-component.

56. (New) The method of claim 51, wherein the step of disposing the micro-component in the socket comprises using electrostatic sheet transfer to place the micro-component into the socket.

57. (New) The method of claim 51, wherein the step of printing the second electrode over the dielectric layer comprises inkjet printing.

58. (New) The method of claim 53, wherein the liquid dielectric material has a surface tension adapted to provide a uniform thickness across the first substrate.

59. (New) The method of claim 53, wherein the liquid dielectric material includes a surfactant.

60. (New) The method of claim 51, further comprising: disposing an RF screen over the top layer.

61. (New) The method of claim 51, further comprising: coating the micro-component with a phosphor material

62. (New) The method of claim 51, further comprising:

immersing the micro-component in a slurry of phosphor particles to form a phosphor coating; and

curing the phosphor coating formed on the micro-component.

63. (New) The method of claim 54, further comprising:

depositing a liquid black mask layer onto the first substrate and the conductive ink; and

curing the liquid mask material to form a black mask layer.

64. (New) A method for forming a flexible light emitting panel comprising:

feeding a first dielectric substrate material from a payout reel in a web coating machine;

printing a first electrode on the first dielectric material;

forming a socket at a location in the first dielectric material;

disposing a micro-component adapted to emit light in the socket;

aligning a second sheet material having dielectric properties over the first dielectric substrate material and the first electrode, wherein the second dielectric sheet material has an opening therethrough corresponding to the location, the opening having a diameter larger than an outer diameter of the micro-component; so that a gap is created between an inner diameter of each opening and the outer diameter of each micro-component;

providing a dielectric material over at least a portion of the second sheet material so that the gap corresponding to the micro-component is filled;

printing a second electrode over the second sheet material; and

applying a top layer over the second sheet material, the second electrode and the micro-component.

65. (New) The method of claim 64, wherein the step of provide the dielectric material comprises:

applying a liquid dielectric material over at least a portion of the second sheet material so that the gap corresponding to the micro-component is filled, the liquid

dielectric material having dielectric properties adapted for control of electric field and breakdown characteristics of the micro-component; and

curing the liquid dielectric material.

66. (New) The method of claim 64, wherein the step of printing the second electrode comprises:

printing the second electrode over the second sheet material using a conductive ink; and

curing the conductive ink.

67. (New) The method of claim 64, further comprising:

applying an adhesive material within the socket for securing the micro-component in the socket.

68. (New) The method of claim 64, wherein the step of disposing the micro-component in the socket comprises:

using electrostatic sheet transfer to place the micro-component into the socket.

69. (New) The method of claim 64, wherein the step of printing the second electrode comprises inkjet printing.

70. (New) The method of claim 30, wherein the liquid dielectric material includes a surfactant.

71. (New) The method of claim 64, further comprising disposing an RF screen over the top layer.

72. (New) The method of claim 64, further comprising: coating the micro-component with a phosphor material.

73. (New) The method of claim 64, further comprising:

immersing the micro-component in a slurry of phosphor particles to form a phosphor coating; and

curing the phosphor coating formed on the micro-component.

74. (New) The method of claim 64, further comprising:

depositing a liquid black mask layer onto the first substrate and the conductive ink; and

curing the liquid mask material to form a black mask layer.